

XP3A010AMT

Halogen-Free Product

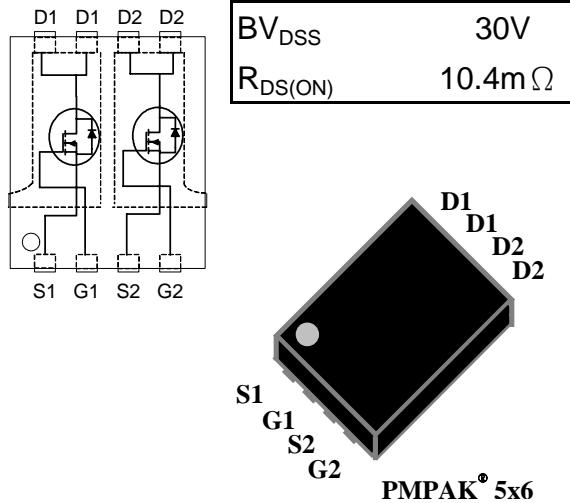
YAGEO
XSEMI

**DUAL N-CHANNEL ENHANCEMENT
MODE POWER MOSFET**

- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free

Description

XP3A010A series are innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for PMPAK® 5x6 dual pad provide superior thermal performance and is design for surface mount applications.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	+20	V
$I_D @ T_C=25^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}^4$	35	A
$I_D @ T_A=25^\circ\text{C}$	Drain Current ³ , $V_{GS} @ 10\text{V}$	12	A
$I_D @ T_A=70^\circ\text{C}$	Drain Current ³ , $V_{GS} @ 10\text{V}$	11.5	A
I_{DM}	Pulsed Drain Current ¹	50	A
$P_D @ T_A=25^\circ\text{C}$	Total Power Dissipation	3.57	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Rating	Units
R_{thj-c}	Maximum Thermal Resistance, Junction-case	6	°C/W
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	35	°C/W

Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=250\mu\text{A}$	30	-	-	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=12\text{A}$	-	-	10.4	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=7\text{A}$	-	-	15.3	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=1\text{mA}$	1.45	-	3	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_{\text{D}}=10\text{A}$	-	40	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$	-	-	25	μA
I_{GSS}	Gate-Source Leakage	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Q_{g}	Total Gate Charge	$I_{\text{D}}=7\text{A}$	-	14	22.4	nC
Q_{gs}	Gate-Source Charge	$V_{\text{DS}}=15\text{V}$	-	4.5	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=4.5\text{V}$	-	5.3	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DS}}=15\text{V}$	-	9	-	ns
t_{r}	Rise Time	$I_{\text{D}}=1\text{A}$	-	8	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time	$R_{\text{G}}=3.3\Omega$	-	29	-	ns
t_{f}	Fall Time	$V_{\text{GS}}=10\text{V}$	-	9	-	ns
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	1530	2448	pF
C_{oss}	Output Capacitance	$V_{\text{DS}}=15\text{V}$	-	225	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	160	-	pF
R_{g}	Gate Resistance	$f=1.0\text{MHz}$	-	2.5	5	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_{\text{S}}=2.9\text{A}$, $V_{\text{GS}}=0\text{V}$	-	-	1.2	V
t_{rr}	Reverse Recovery Time	$I_{\text{S}}=12\text{A}$, $V_{\text{GS}}=0\text{V}$, $dI/dt=100\text{A}/\mu\text{s}$	-	11	-	ns
			-	4	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, $t \leq 10\text{sec}$; $85^\circ\text{C}/\text{W}$ on steady state.
- 4.Package limitation current is 12A .

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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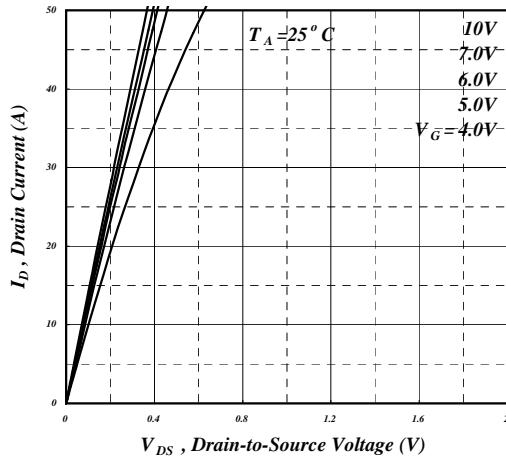


Fig 1. Typical Output Characteristics

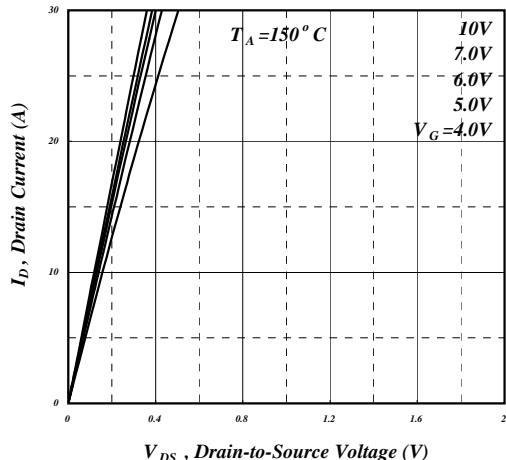


Fig 2. Typical Output Characteristics

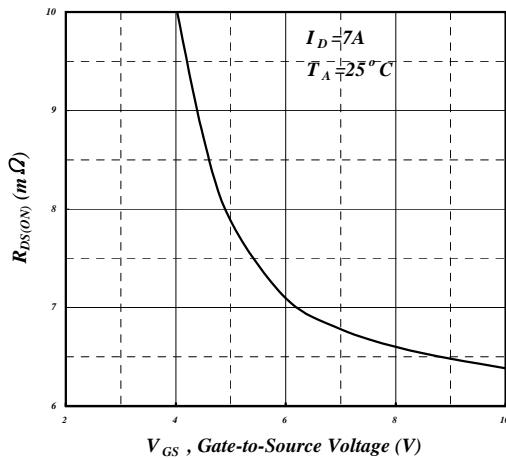


Fig 3. On-Resistance v.s. Gate Voltage

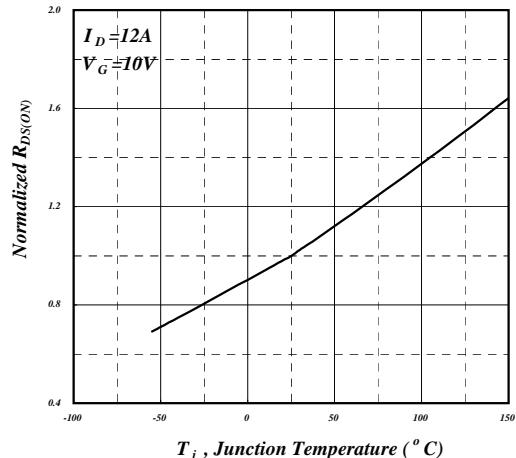


Fig 4. Normalized On-Resistance v.s. Junction Temperature

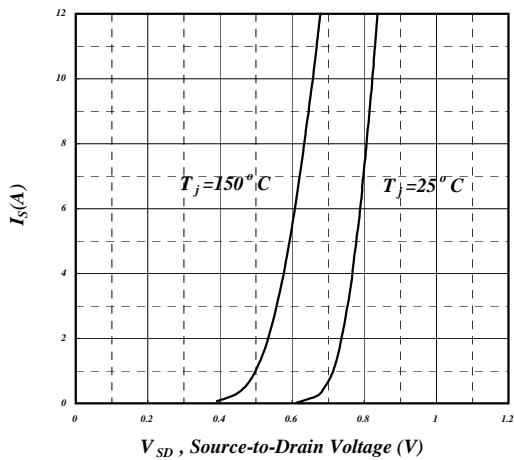


Fig 5. Forward Characteristic of Reverse Diode

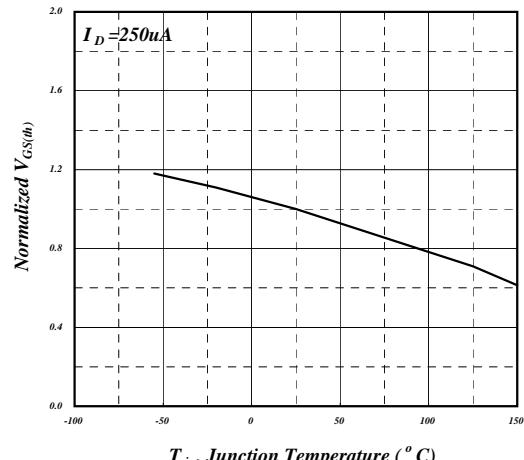


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

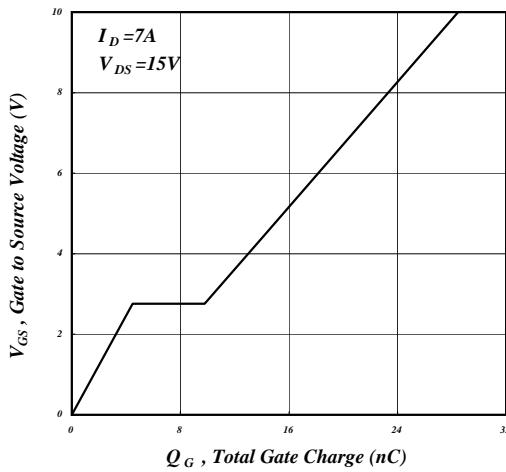


Fig 7. Gate Charge Characteristics

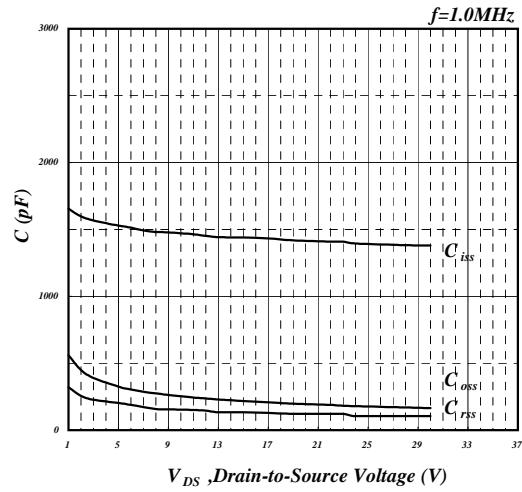


Fig 8. Typical Capacitance Characteristics

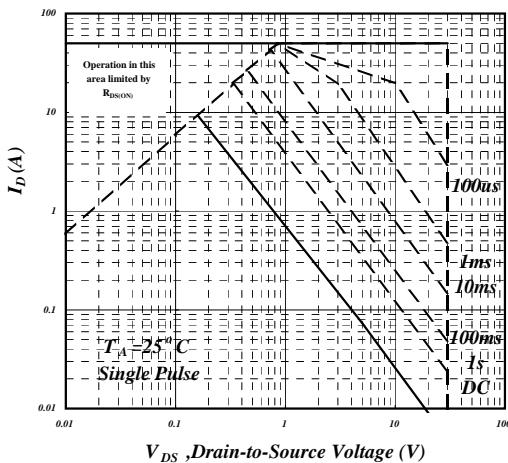


Fig 9. Maximum Safe Operating Area

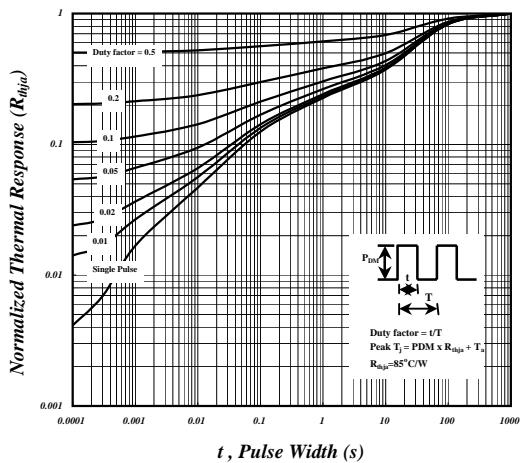


Fig 10. Effective Transient Thermal Impedance

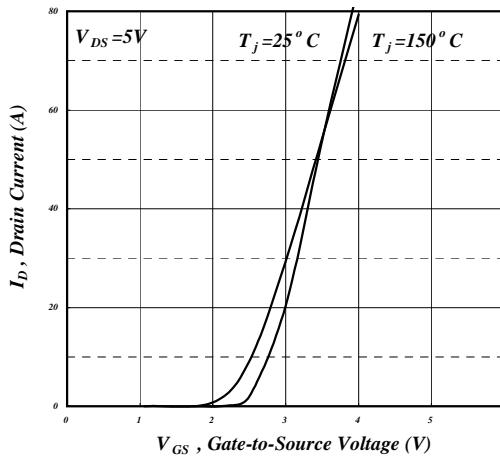


Fig 11. Transfer Characteristics

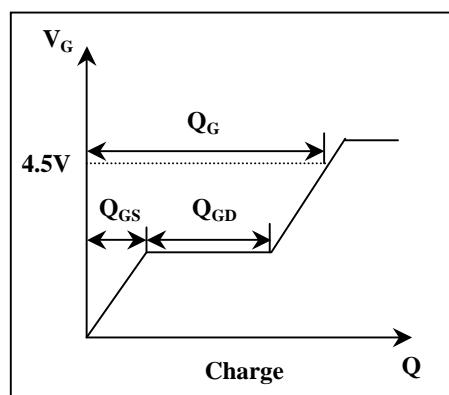
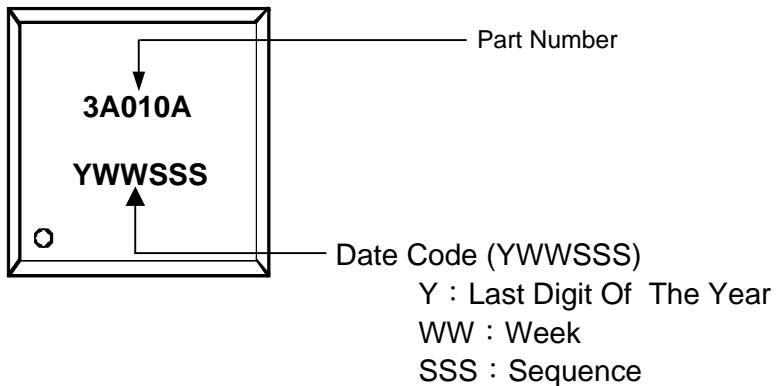
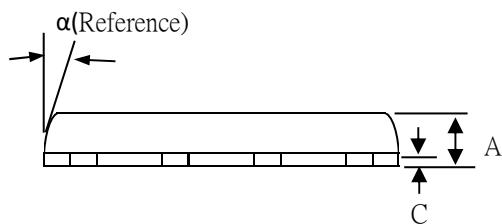
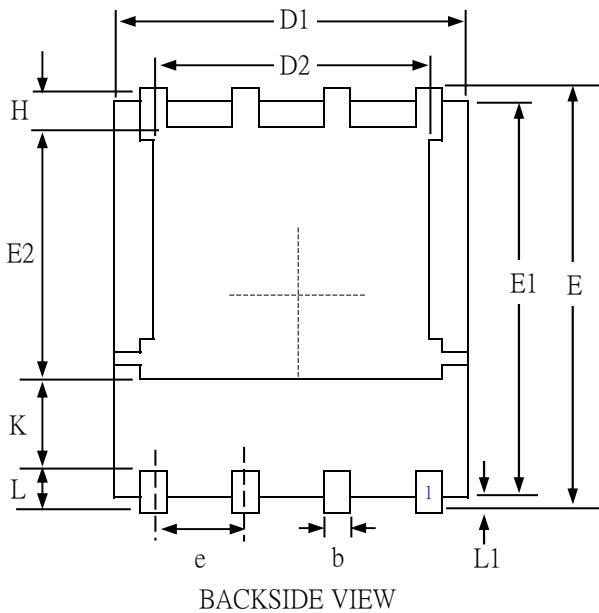


Fig 12. Gate Charge Waveform

MARKING INFORMATION

Package Outline : PMPAK 5x6



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	0.90	1.10	1.30
b	0.33	0.41	0.51
C	0.254(Ref.)		
D1	4.80	4.90	5.10
D2	3.61	4.00	4.40
E	5.80	6.03	6.25
E1 (Ref.)	5.60	5.75	5.90
E2 (Ref.)	3.30	3.55	3.80
e	1.27 BSC		
H	0.35	—	0.90
K (Ref.)	1.00	1.275	—
L	0.35	0.55	0.75
L1	0.06	0.13	0.20
α (Ref.)	0°	—	12°

1. All dimension are in millimeters.
2. Dimension does not include burrs and mold flash/protrusions.
3. The outline schematic is not to scale and slightly different from the actual product appearance.

PMPAK 5X6(E-TYPE) FOOTPRINT :

